

# ELSFP

## External Laser Small Form Factor Pluggable

*Eliminate CPO switch downtime with modular 'hot-swappable' laser sources*

The External Laser Small Form-Factor Pluggable (ELSFP) is a pioneering blind-mating optical and electrical interconnect in a convenient pluggable industry recognized OSFP footprint. The ELSFP is optimized to support next-generation Co-Packaged optics (CPO) requiring a remote laser source.

## Module and Host Connectors

SENKO's innovative design allows the laser module to be quickly and easily 'blind-mated' to the host connectors mounted within the CPO switch.

**MODULE CONNECTOR**

**HOST CONNECTOR**



SENKO's **SN-MT16** Connectivity enhances face-plate density and frees up space for ELSFP modules

### FEATURES

- Reduced overall system thermal power density
- Fast 'plug & play' design for fast deployment
- Compact design enables maximum face-plate density
- A single ELSFP can support multiple OEs
- Hot swappable to prevent system downtime
- Laser-safe design
- Industry recognized OSFP footprint
- PM fiber assemblies for the interconnect between ELSFP and CPO engines

**Hyperscale  
Densification with VSFF  
Connectivity**

Standardized by **OIF**

